

Title (en)
APPARATUS AND METHOD FOR POLISHING A SURFACE OF A SUBSTRATE

Title (de)
VORRICHTUNG UND VERFAHREN ZUM POLIEREN EINER OBERFLÄCHE EINES SUBSTRATS

Title (fr)
APPAREIL ET PROCÉDÉ DE POLISSAGE D'UNE SURFACE D'UN SUBSTRAT

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Abstract (en)
An apparatus which can polish an entirety of a surface of a substrate, such as a wafer, is disclosed. The apparatus according to the present invention includes a substrate holder configured to hold a substrate and rotate the substrate; and a polishing head configured to rub a polishing tool against a first surface of the substrate to polish the first surface. The substrate holder includes a plurality of rollers which can contact a periphery of the substrate. The plurality of rollers are rotatable about their respective own axes.

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